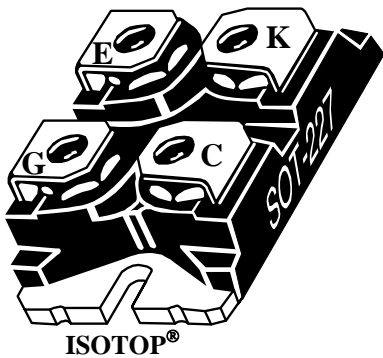
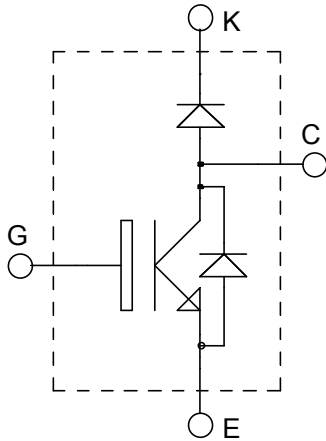


**ISOTOP[®] Boost chopper
NPT IGBT
SiC chopper diode**

**$V_{CES} = 600V$
 $I_C = 30A @ T_c = 90^{\circ}C$**



Application

- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction
- Brake switch

Features

- **Non Punch Through (NPT) Fast IGBT**
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 100 kHz
 - Low leakage current
 - RBSOA and SCSOA rated
- **Chopper SiC Schottky Diode**
 - Zero reverse recovery
 - Zero forward recovery
 - Temperature Independent switching behavior
 - Positive temperature coefficient on VF
- ISOTOP[®] Package (SOT-227)
- Very low stray inductance
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T_C of V_{CEsat}
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{CES}	Collector - Emitter Breakdown Voltage	600	V
I_C	Continuous Collector Current	$T_C = 25^{\circ}C$	45
		$T_C = 90^{\circ}C$	30
I_{CM}	Pulsed Collector Current	$T_C = 25^{\circ}C$	100
V_{GE}	Gate - Emitter Voltage	± 20	V
P_D	Maximum Power Dissipation	$T_C = 25^{\circ}C$	154
RBSOA	Reverse Bias Safe Operating Area	$T_j = 125^{\circ}C$	60A@500V

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0\text{V}$ $V_{CE} = 600\text{V}$	$T_j = 25^\circ\text{C}$			250	μA
			$T_j = 125^\circ\text{C}$			500	
$V_{CE(on)}$	Collector Emitter on Voltage	$V_{GE} = 15\text{V}$ $I_C = 30\text{A}$	$T_j = 25^\circ\text{C}$	1.7	2.0	2.45	V
			$T_j = 125^\circ\text{C}$		2.2		
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 1\text{mA}$	4		6	V	
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20\text{V}, V_{CE} = 0\text{V}$			400	nA	

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{ies}	Input Capacitance	$V_{GE} = 0\text{V}$ $V_{CE} = 25\text{V}$ $f = 1\text{MHz}$		1350		pF
C_{oes}	Output Capacitance			193		
C_{res}	Reverse Transfer Capacitance			120		
Q_g	Total gate Charge	$V_{GE} = 15\text{V}$ $V_{Bus} = 300\text{V}$ $I_C = 30\text{A}$		99		nC
Q_{ge}	Gate – Emitter Charge			10		
Q_{gc}	Gate – Collector Charge			60		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) $V_{GE} = 15\text{V}$ $V_{Bus} = 400\text{V}$ $I_C = 30\text{A}$ $R_G = 6.8\Omega$		30		ns
T_r	Rise Time			12		
$T_{d(off)}$	Turn-off Delay Time			80		
T_f	Fall Time			15		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) $V_{GE} = 15\text{V}$ $V_{Bus} = 400\text{V}$ $I_C = 30\text{A}$ $R_G = 6.8\Omega$		32		ns
T_r	Rise Time			12		
$T_{d(off)}$	Turn-off Delay Time			90		
T_f	Fall Time			21		
E_{on}	Turn-on Switching Energy	$V_{GE} = 15\text{V}$ $V_{Bus} = 400\text{V}$ $I_C = 30\text{A}$ $R_G = 6.8\Omega$	$T_j = 125^\circ\text{C}$		0.2	mJ
E_{off}	Turn-off Switching Energy				0.8	
I_{sc}	Short Circuit data	$V_{GE} \leq 15\text{V}; V_{Bus} = 360\text{V}$ $t_p \leq 10\mu\text{s}; T_j = 125^\circ\text{C}$		135		A

Chopper SiC diode ratings and characteristics

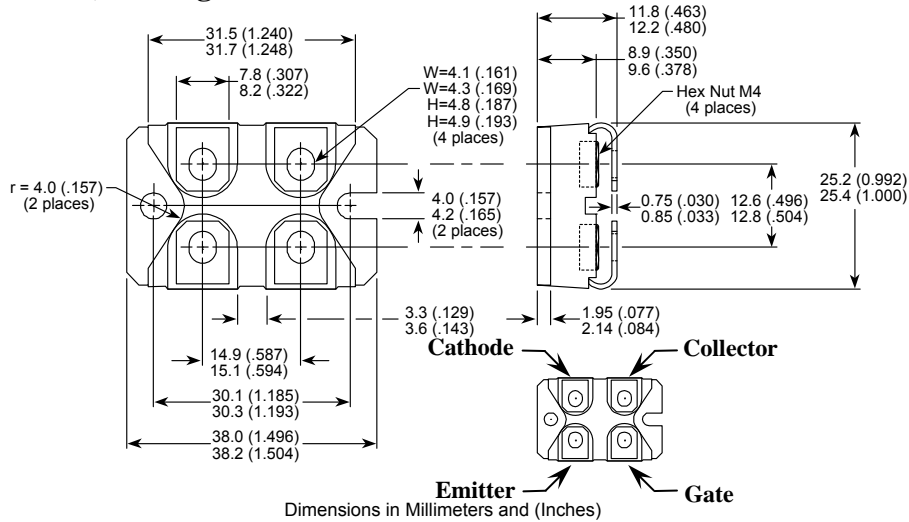
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		600			V	
I_{RM}	Maximum Reverse Leakage Current	$V_R = 600\text{V}$	$T_j = 25^\circ\text{C}$		50	200	μA
			$T_j = 175^\circ\text{C}$		100	2000	
I_F	DC Forward Current			10		A	
V_F	Diode Forward Voltage	$I_F = 10\text{A}$	$T_j = 25^\circ\text{C}$	1.6	1.8	V	
			$T_j = 175^\circ\text{C}$	2	2.4		
Q_C	Total Capacitive Charge	$I_F = 10\text{A}, V_R = 300\text{V}$ $di/dt = 500\text{A}/\mu\text{s}$		14		nC	
C	Total Capacitance	$f = 1\text{MHz}, V_R = 200\text{V}$		65		pF	
		$f = 1\text{MHz}, V_R = 400\text{V}$		50			

Thermal and package characteristics

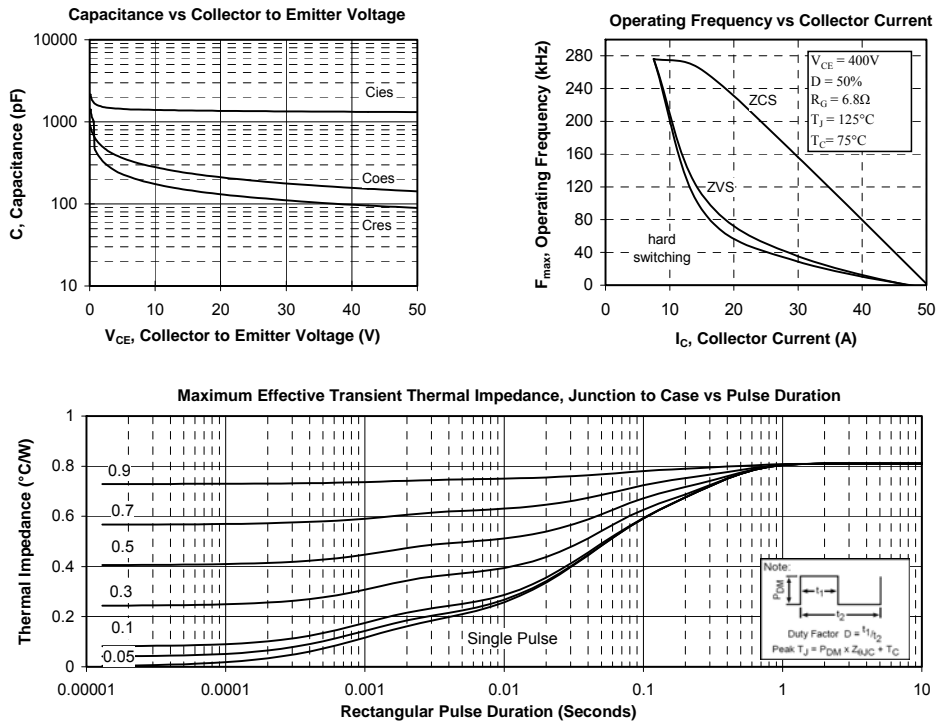
Symbol Characteristic

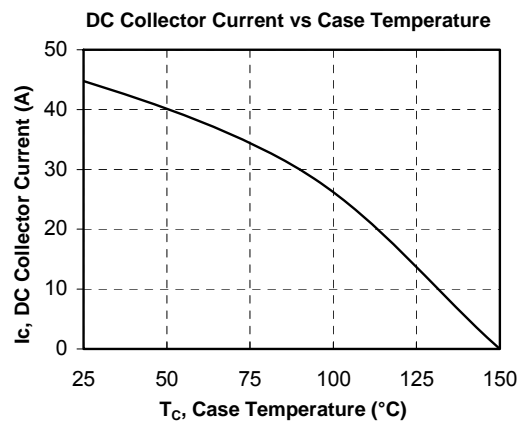
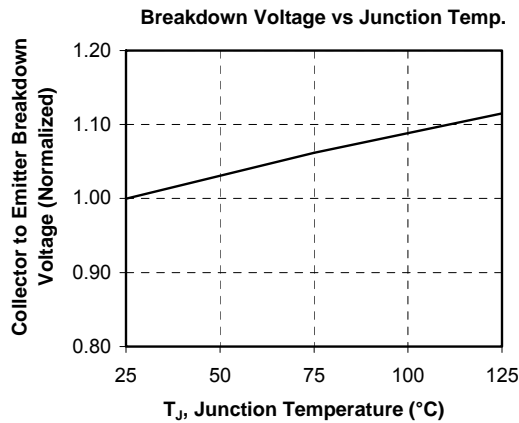
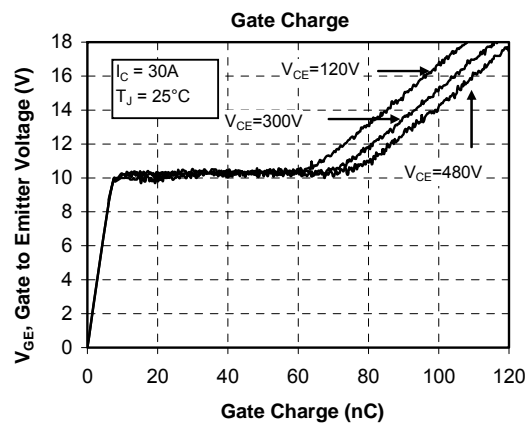
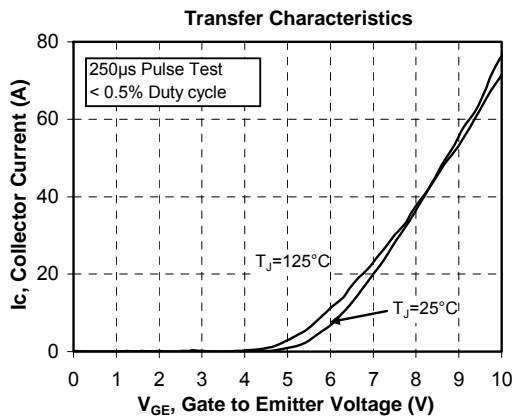
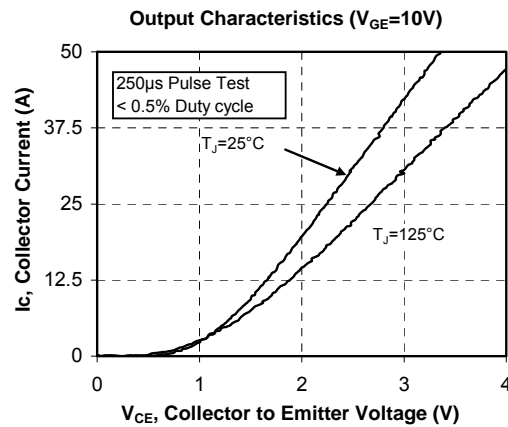
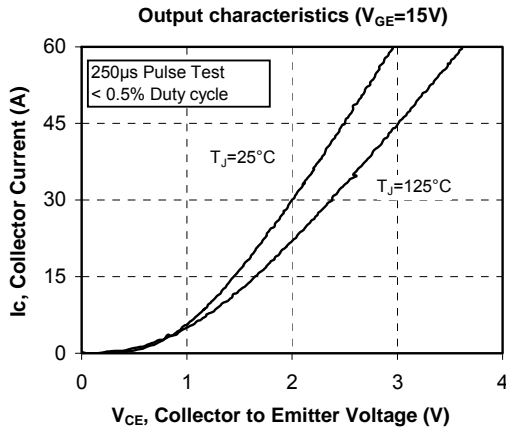
		Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance	IGBT		0.81	°C/W
		SiC chopper Diode		2.25	
R_{thJA}	Junction to Ambient (IGBT & Diode)			20	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, I isol<1mA, 50/60Hz	2500			V
T_J, T_{STG}	Storage Temperature Range	-55		150	°C
T_L	Max Lead Temp for Soldering:0.063" from case for 10 sec			300	
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

SOT-227 (ISOTOP®) Package Outline

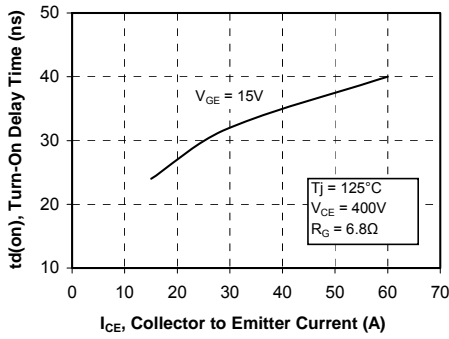


Typical IGBT Performance Curve

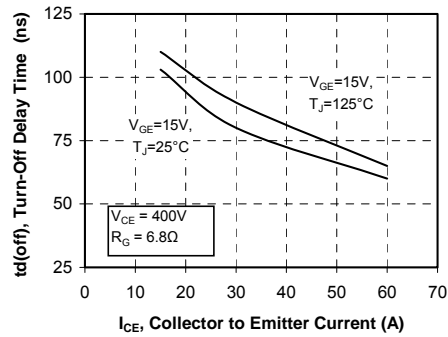




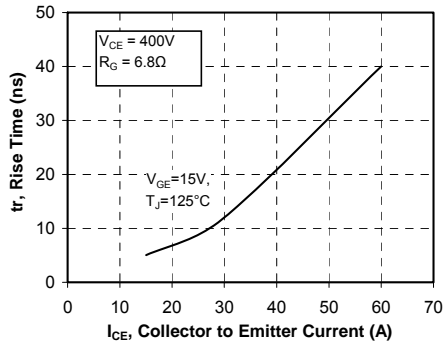
Turn-On Delay Time vs Collector Current



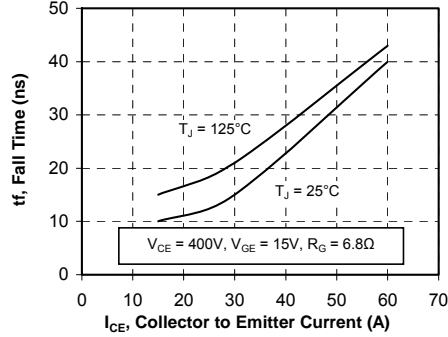
Turn-Off Delay Time vs Collector Current



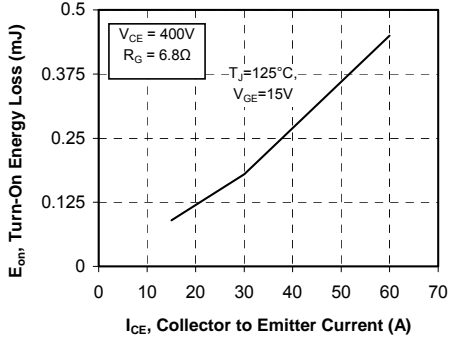
Current Rise Time vs Collector Current



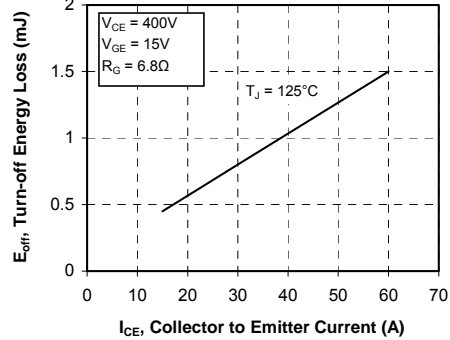
Current Fall Time vs Collector Current



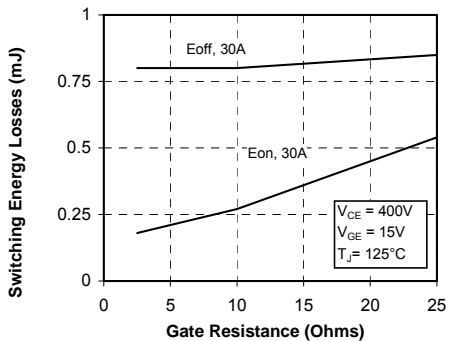
Turn-On Energy Loss vs Collector Current



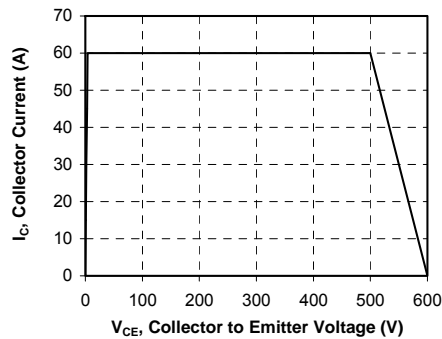
Turn-Off Energy Loss vs Collector Current



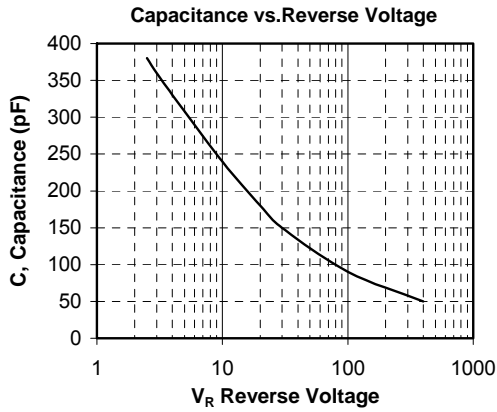
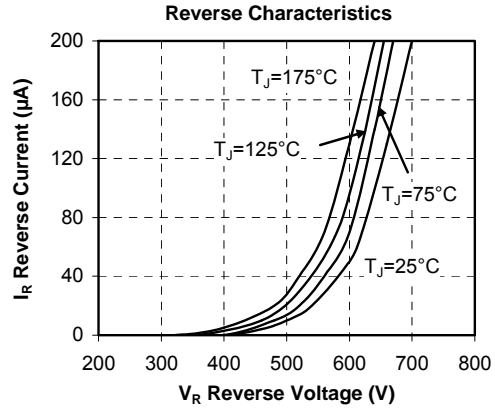
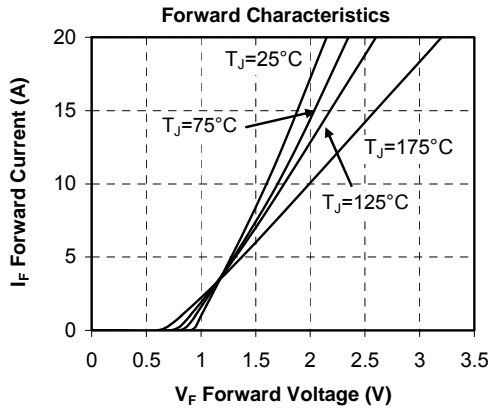
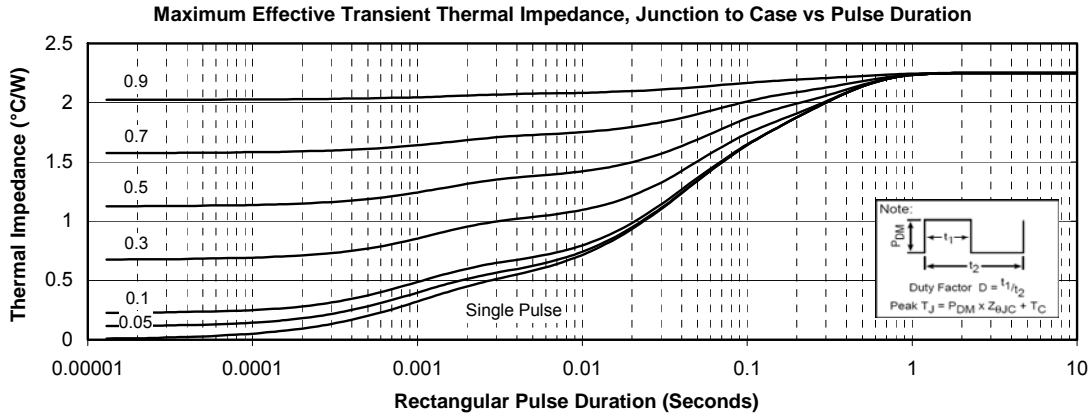
Switching Energy Losses vs Gate Resistance



Reverse Bias Safe Operating Area



Typical SiC chopper diode Performance Curve



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Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 6,939,743 7,352,045 5,283,201 5,801,417 5,648,283 7,196,634 6,664,594 7,157,886 6,939,743 7,342,262 and foreign patents. U.S. and Foreign patents pending. All Rights Reserved.